

HYPREZ® Diamond Compounds

With more than 80 years of experience, Engis is a world leader in the manufacture of high-quality diamond compound offering the widest range of products in the industry.

Hyprez compound formulas are the result of Engis' complete understanding of diamond and its application in the lapping and polishing processes. Our expertise on how to mill, shape and grade diamond is unmatched. Coupled with this experience is our knowledge of chemistry and compounding techniques ensuring superior stock removal and surface finishes.



DIAMOND COMPOUND TYPES

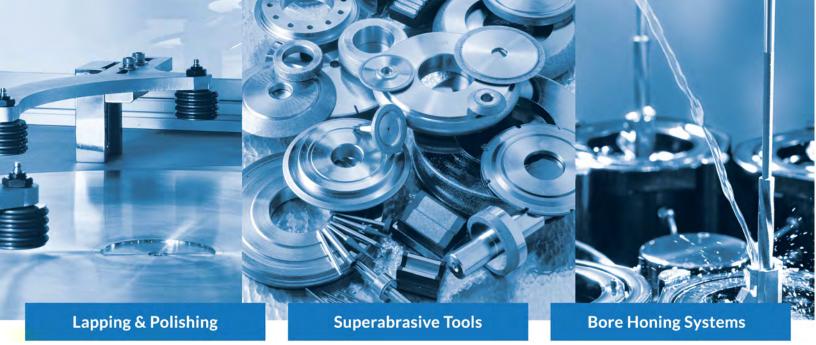
DIAMOND PASTES - thick formulations dispensed from a syringe or jar and manually spread across the part. Pastes are the most commonly used form of diamond compound for hand polishing and typically used with a companion lubricant. (Packed in 5, 18, 50 or 100 gram syringe, 10 gram Hyplicator® or 100 / 500 gram jar.)

DIAMOND GELS - thinner than pastes, but still thick enough to be applied with a syringe. The thinner consistency results in slower drying, reducing scratching on larger parts, while maintaining good adhesion to lapping tools and parts. Great for automated or hand polishing. (Packed in 18 or 100 gram syringe.)

FLOWABLE COMPOUNDS - can be poured or pumped for applications using automated polishing. The thick formulation will flow around the part while maintaining good adhesion. (Packed in pint (400g) bottle.)

COMPOUND	DESCRIPTION	LUBRICANT
Five-Star	Combines excellent cutting characteristics of blended natural and synthetic diamonds in a carrier that is both water and oil soluble. This compound is the flagship of our diamond compounds and is recognized as a premium products in Asia, Europe and the Americas.	OS-IV or W
Hyprez L	An oil soluble compound designed for use on hard materials such as carbides or ceramics.	OS-IV
Hyprez OS	This oil based compound is self-lubricating and ideal for rapid stock removal applications.	OS-IV
Hyprez W	A water based formulation that permits easy cleaning from the workpiece. Especially suitable for high luster polishing.	W
Hyprez SC	Formulated with the polishing professional in mind. Oil based formulation incorporating an exceptionally sharp diamond type and particle size distribution resulting in superior cutting action.	OS-IV

Engis can customize other packaging types and unit sizes to meet production application requirements. Available in diamond sizes of 0.1, 0.25, 0.5, 1, 3, 6, 9, 15, 30, 46 and 60 micron.





Engis® offers state-of-the-art technology in the design of flat lapping systems that meet the most demanding requirements.



We offer a complete range of superabrasive electroplated products for precision applications.



Multi-Stroke Honing, Single-Pass Bore Finishing & Single-Pass Dual Bore Finishing Systems, Complete Machine Design, Tools & Process Development

Superabrasive Powders



We manufacture high-quality micron diamond & CBN with properties that ensure consistent performance in each application

Mold & Die Polishing



Engis[®] long trusted brands include Five-Star[®] diamond compound.

Engis Global Presence



US Engis Corporation



Engis Japan Co., Ltd.



Engis Lapping & Grinding Technology Co., Ltd.



Engis Asia Pacific Pte. Ltd.



Engis of Canada, Ltd.



Engis (Hong Kong) Ltd.



Engis Korea Co., Ltd.



Engis UK Ltd. EUROPEAN OPERATIONS



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